

1.26 W/mK

An electrically isolating material, 5308 was designed specifically for underfilling, staking and encapsulating electronics on circuit boards, as well as potting and encapsulating power supplies, transformers, and coils. Featuring a 3-hour pot life, 5308 has good flowability, making it ideal for applications requiring a self-leveling material. The material meets NASA's outgassing requirements, is resistant to solvents and chemicals, and is considered non-hazardous per D.O.T. regulations.

UNCURED	
Pot Life @ 25°C	3 hours
Viscosity @ 25°C	100,000 cPs
Shelf Life @ -40°C	12 Months (Cryo-Pac®)
Shelf Life @ 25°C	12 Months (Appli-Pac®)
Mix Ratio	100A:2.38B Parts By Weight
CURE OPTIONS	2 hours @ 80°C 4 hours @ 60°C
CURED PROPERTIES	Based on cure of 2 hours @ 80°C
Color	Black
Shore D Hardness	90
Glass Transition Temp (°C)	100
Density (g/cc)	2.46
Lap Shear 2024T3 Clad (psi)	2,000
Shrinkage Linear (%)	0.17
CURED PROPERTIES	Based on cure of 4 hours @ 60°C
Shrinkage Linear (%)	0.04
ELECTRICAL PROPERTIES	Based on cure of 2 hours @ 80°C
Dielectric Constant	5.5 @ 100 kHz
Dissipation Factor	0.01 @ 100 kHz
Dielectric Strength (volts/mil)	445
Volume Resistivity (ohm-cm)	4.0E 15 @ 500 VDC
THERMAL PROPERTIES	Based on cure of 2 hours @ 80°C
Coefficient of Thermal Expansion, ppm/°C	Below Tg: 33; Above Tg: 103
Degradation Temp (°C)	300
Thermal Conductivity (W/mK)	1.26
OUTGASSING PROPERTIES	Based on cure of 2 hours @ 80°C
TML (%)	0.12
CVCM (%)	0.01
WVR (%)	0.04
ACOUSTIC PROPERTIES	
Velocity (m/s)	3,124
Impedance (MRayles)	7.69
Loss (dB/cm-MHz)	-7.71
Density (g/cc)	2.46

KEY FEATURES

D.O.T. Non-Hazardous

Electrically Isolating

High Glass Transition Temperature

High Temperature Resistant

High Thermal Conductivity

Low Shrinkage

Flowable

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